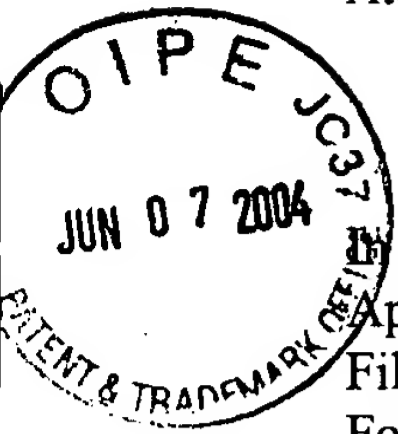


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Atty. Dkt. No: AMK-11443



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

By re application of: Lee John Smith et al.

Application No.: 09/944,732

Art Unit.: 2827

Filing Date: 08/31/2001

Examiner: David Graybill

For: "THIN SEMICONDUCTOR PACKAGE INCLUDING STACKED DIES"

Mail Stop Non-Fee Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Date: June 1, 2004

AMENDMENT TRANSMITTAL

1. Transmitted herewith is an amendment for this application.
2. **STATUS:** Applicant is other than a small entity.
3. **EXTENSION OF TERM:** The proceedings herein are for a patent application and the provisions of 37 C.F.R. 1.136 apply. Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. **FEE FOR CLAIMS:** The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

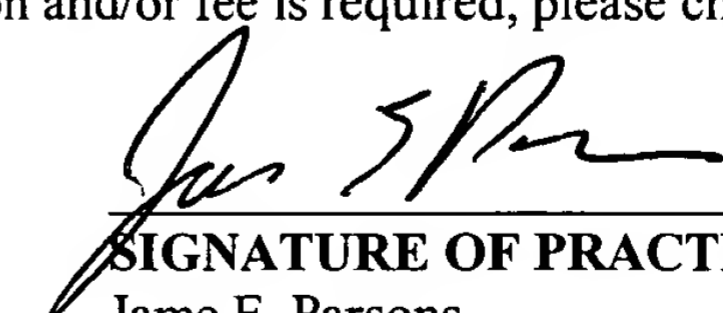
	(Col.1)		(Col. 2)	(Col. 3)	LARGE ENTITY	
	Claims Remaining After Amendment		Highest No. Previously Paid For	Present Extra	Rate	Addit. Fee
Total	9	Minus	25	= 0	x \$18 =	\$0
Indep.	1	Minus	5	= 0	x \$86 =	\$0
First Presentation of Multiple Dependent Claim					+ \$290 =	\$0
					Total Addit. Fee	\$0

No additional fee for claims is required.

5. **FEE DEFICIENCY:** If any additional extension and/or fee is required, please charge Deposit Account No. 50-0574.

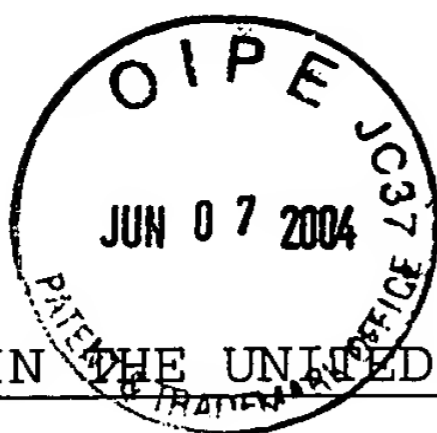
Customer No. 022888

Tel.: (408) 451-5906


SIGNATURE OF PRACTITIONER
Jame E. Parsons
Reg. No. 34,691

I hereby certify that this correspondence is being deposited with the United States Postal Service as FIRST CLASS MAIL in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 1, 2004.

Date: 6/1/2004
Signature: Rebecca A. Baumann



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lee John Smith et al.

Assignee: Amkor Technology, Inc.

Title: Thin Semiconductor Package Including Stacked Dies

Serial No.: 09/944,732-2003 File Date: 8/31/01

Examiner: Graybill, David Art Unit: 2827

Docket No.: AMK-11443

Date: June 1, 2004

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT IN RESPONSE TO THE OFFICE ACTION OF 3/3/04

Dear Sir:

In response to the first Office Action mailed from the Patent Office on March 3, 2004, please amend the application as follows.